

## RT/duroid® 5880 LZ Quick Reference Processing Guide

Material Description	Copper-clad filled PTFE composite
Storage:	Ambient
<b>INNER LAYER PREPARATION</b>	
Tooling:	Compatible with most round and slotted hole systems.
Surface Preparation for Photoresist Applications:	Chemical preparation.
Photoresist Applications:	Standard film and liquid resists and procedures.
DES Processing:	Standard processing. Thin cores may require leaders.
Oxide Treatment:	Use procedures associated with oxide or oxide alternative of choice.
<b>BONDING</b>	
Final Preparation:	125°C to 150°C pre-bake required.
Multilayer Adhesive System:	Compatible with most thermoplastic and thermoset films.
Multilayer Bond Cycle:	Use bond parameters associated with adhesive system.
<b>PTH PROCESSING</b>	
Drilling:	Rigid and supportive entry/exit materials such as press phenolic. Use new drills. Controlled infeeds, speeds, and retract rates. 12" rule for hole.
Deburring:	Mechanical debur/scrub not recommended. Very light applied pressure if debur is required.
Hole Preparation:	Pressurized water or air purge of holes is okay. Sodium or plasma treatments required prior to metal deposition. Bake required after sodium treatment.
Metallization:	Electroless copper (low or regular dep rates preferred over heavy dep processes) or direct deposit processes. Flash plate recommended prior to outer-layer imaging.
<b>OUTER LAYER IMAGING AND FINISHING</b>	
Standard image, plate, etch and strip procedures apply.	
Final Surfaces:	Compatible with most final metals surfaces and OSP's. Preserve post-etch surface and bake cores prior to application of LPI.
Final Circuitization:	Rout and punch as required. Material support and sharp edges on cutting tools required through mechanical processes.

The information in this processing guideline is intended to assist you in designing with Rogers' circuit material laminates. It is not intended to and does not create any warranties express or implied, including any warranty of merchantability or fitness for a particular purpose or that the results shown on this processing guideline will be achieved by a user for a particular purpose. The user should determine the suitability of Rogers' circuit material laminates for each application.

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